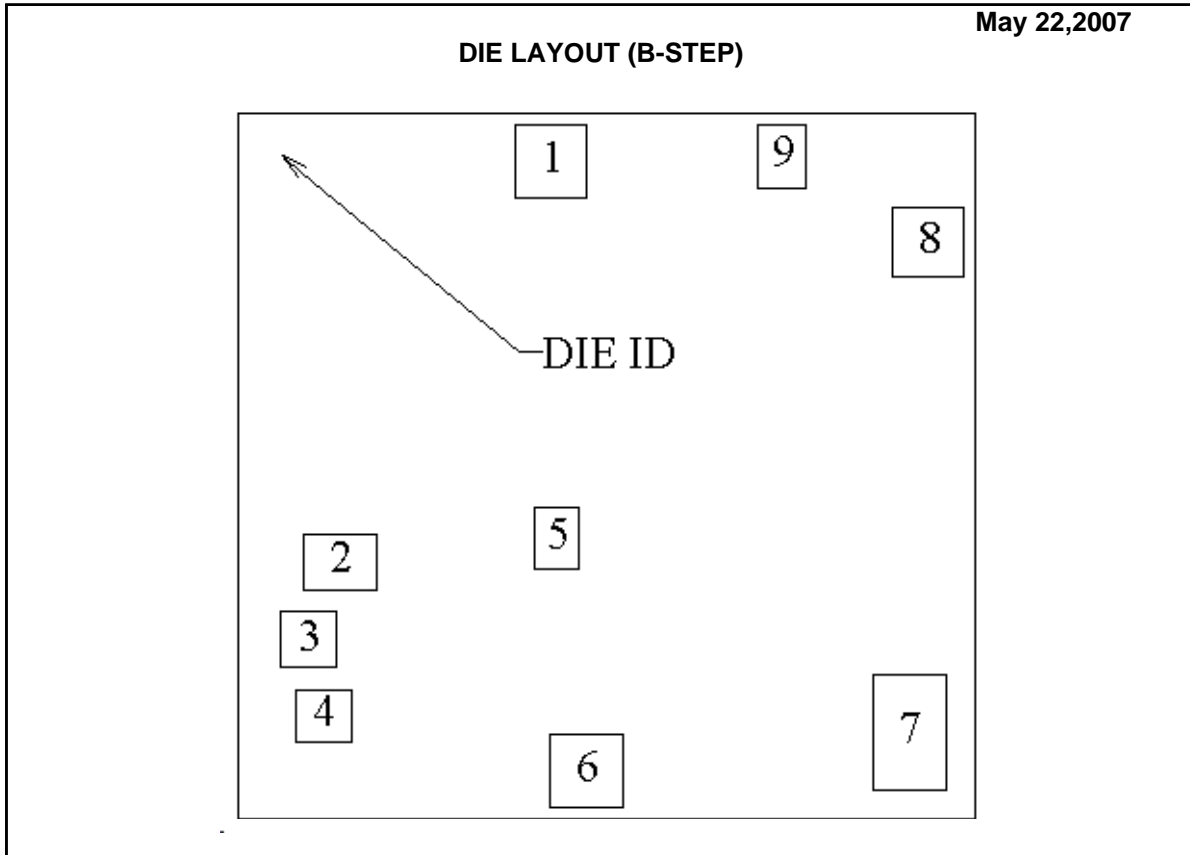


**LM136-2.5 MDS MCD2570A  
VOLTAGE REFERENCE DIODE**



**DIE/WAFER CHARACTERISTICS**

| <b>Fabrication Attributes</b> |  | <b>General Die Information</b> |                           |
|-------------------------------|--|--------------------------------|---------------------------|
| Physical Die Identification   | 136B   | Bond Pad Opening Size (min)    | 117 $\mu$ m x 112 $\mu$ m |
| Die Step                      | B  | Bond Pad Metalization          | ALUMINUM                  |
| <b>Physical Attributes</b>    |  | Passivation                    | VOM NITRIDE               |
| Wafer Diameter                | 150mm  | Back Side Metal                | GOLD BACK                 |
| Die Size (Drawn)              | 1194 $\mu$ m x 1143 $\mu$ m<br>47.0mils x 45.0mils | Back Side Connection           | Floating or -             |
| Thickness                     | 330 $\mu$ m Nominal                                |                                |                           |
| Min Pitch                     | 626 $\mu$ m Nominal                                |                                |                           |

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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| Die Bond Pad Coordinate Locations (B -Step)   |        |                 |      |          |   |     |
|---|--------|-----------------|------|----------|---|-----|
| (Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used |        |                 |      |          |   |     |
| SIGNAL  | PAD#   | X/Y COORDINATES |      | PAD SIZE |   |     |
| NAME  | NUMBER | X               | Y    | X        | Y |     |
| ADJ   | 1      | -91             | 495  | 117      | x | 117 |
| NC  | 2      | -432            | -155 | 117      | x | 91  |
| NC  | 3      | -483            | -282 | 91       | x | 91  |
| NC  | 4      | -460            | -406 | 91       | x | 86  |
| NC  | 5      | -81             | -117 | 71       | x | 97  |
| +   | 6      | -33             | -495 | 117      | x | 117 |
| NC  | 7      | 491             | -432 | 119      | x | 188 |
| -   | 8      | 521             | 363  | 117      | x | 112 |
| NC  | 9      | 284             | 502  | 81       | x | 104 |

**LM136-2.5 MDS MCD2570A**  
**VOLTAGE REFERENCE DIODE**

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|                               |  |
|-------------------------------|--|
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